CLAIMS

1. A silver powder comprising:

silver particles; and

an adherent that is attached to surfaces of the silver particles and contains a metal oxide that has a melting point lower than a melting point of silver,

wherein the metal oxide is at least one of a Te oxide, a Bi oxide, a Pb oxide, a Tl oxide, and a V oxide,

a volume-based cumulative 50% particle size (D50) is 0.5 μm to 4 μm.

2. The silver powder according to claim 1,

wherein an amount of a metal component that constitutes the metal oxide is 0.01 mass% to 10 mass% relative to an amount of silver contained in the silver powder.

3. The silver powder according to claims 1 or 2,

wherein the adherent includes a first adherent that contains the metal oxide and a second adherent that contains a metal that is the metal component that constitutes the metal oxide or an alloy made of the metal component and silver.

4. The silver powder according to claim 3,

wherein the metal component is at least one of Te, Bi, Pb, Tl, and V.

5. The silver powder according to any one of claims 1 to 4,

wherein a total amount of the metal component, excluding silver and contained in the adherent, that constitutes the metal oxide of the adherent is 0.1 mass% to 10 mass% relative to an amount of silver contained in the silver powder.

6. A method for producing the silver powder according to claim 1, the method comprising the step of:

adding a reducing agent and an aqueous solution that contains a metal component that

constitutes a metal oxide that has a melting point lower than a melting point of silver to a silver complex solution,

wherein the metal oxide of the metal component is deposited on the surfaces of the silver particles to attach the metal oxide of the metal component to the surfaces of the silver particles while the silver particles are deposited through reduction, and thereby forming an adherent that contains the metal oxide that has a melting point lower than a melting point of silver,

the aqueous solution is an aqueous solution in which at least one of Te, Bi, Pb, Tl, and V is dissolved as the metal component, and

a volume-based cumulative 50% particle size (D50) is 0.5 μm to 4 μm.

7. A conductive paste comprising:

the silver powder according to any one of claims 1 to 5;

the silver powder that does not contain a metal component other than silver on a surface of the silver powder thereof excluding unavoidable impurities;

an organic binder;

a glass frit; and

a solvent.

8. The conductive paste according to claim 7,

wherein an amount of the metal component that constitutes the metal oxide contained in the silver powder according to any one of claims 1 to 5 is 0.001 mass% to 0.03 mass% relative to an amount of silver contained in the conductive paste.

9. The conductive paste according to claim 7 or 8,

wherein the glass frit contains a component selected from Pb, Te, Li, Zn, Si, Al and Bi.